



Activated, rosin based, no-clean solder wire

Description:

Interflux[®] **RosIX 705 SnPb(Ag)** is a no-clean solder wire that has been developed to give increased wetting on surfaces that are difficult to solder, e.g. OSP, Ni, Zn, brass, German silver,... as well as on degraded and oxidised surfaces.

The solder wire produces a non disturbing smell while soldering and is pleasant for operators to work with.

RosIX 705 SnPb(Ag) produces cosmetically nice solder joints with a smooth and transparent residue.

RosIX 705 SnPb(Ag) is useable in both hand soldering and automated soldering processes.

The solder wire is activated with a low amount of halides classified as RO L1 according to IPC and EN-standards.



Products pictured may differ from the product delivered

Key properties

- Increased wetting properties on surfaces that are difficult to solder.
- Non disturbing smell
- Smooth transparent residue

Availability

Flux type:	RosIX 705						
Flux content:	2,2% w/w						
		diameters (mm)					
alloy	melting point	0,35	0,50	0,70	1,00	1,50	2,00
Sn60Pb40	~183°C—191°C	●	●	●	●	●	●
Sn63Pb37	~183°C	●	●	●	●	●	●
Sn62Pb36Ag2	~179°C	●	●	●	●	●	●
Note: other alloys and diameters upon request		● = available ● = upon request					



Work Instructions

Manual soldering

The advised working temperature is between 320°C and 360°C. For more dense metals like Nickel, the temperature may be elevated to 400°C. The use of a good soldering station is important. Use a soldering station with a short response time and with enough power for your application. Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact area with the surfaces to be soldered. Heat up both the surfaces simultaneously. Slightly touch with the solder wire, the point where soldering tip and the surfaces to be soldered meet (the small quantity of solder ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. This will reduce the risk on flux spitting and premature flux consumption!

Handling

Storage

Store the solder wire in a clean environment at ambient temperature.

Handling

To avoid spool and wire damage, handle package with care.

Safety

Please always consult the safety datasheet of the product.

Packaging

The standard packaging is a 500g spool.

Other spool sizes upon request



Test results

Conform EN 61190-1-3(2007) and IPC J-STD-004(A)

Property	Result	Method
Chemical		
flux designator	RO L1	J-STD-004A
	F-SW 26	DIN 8511
	1.1.2	ISO 9454
qualitative copper mirror	pass	J-STD-004A IPC-TM-650 2.3.32 D
quantitative halide	< 0,5%	J-STD-004A IPC-TM-650 2.3.35
spot test (F)	pass	J-STD-004A IPC-TM-650 2.3.35.1
total Acid Number (25% sol)	55,94 ± 5 mg KOH/g	J-STD-004A IPC-TM-650 2.3.13
Environmental		
SIR test	pass	J-STD-004 IPC-TM-650 2.6.3.3
qualitative corrosion, flux	pass	J-STD-004A IPC-TM-650 2.6.15
Mechanical		
spread test	155,18 mm²	J-STD-004A IPC-TM-650 2.4.46
dryness test	pass	J-STD-004A IPC-TM-650 2.4.47

Trade name: RosIX 705 leaded, rosin based, activated no-clean solder wire

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